REMARKS

The specification has been reviewed, and clerical errors of the specification have been amended.

In paragraph 2 of the Action, claim 9 was objected to. In paragraphs 4-6 and 8-11 of the Action, claims 1-13 and 22-35 were rejected under 35 U.S.C. 102(b) or 35 U.S.C. 103(A) by Koyama, WO '251 and JP '599. In view of the objection and rejections, claims 1, 7, 10, 22, 28, 31 and 35 have been amended, and claims 2-4, 6, 9, 14-21, 23-25, 27, 30 and 36-40 have been cancelled.

As clearly recited in amended claim 1, a transparent electroconductive film in claim 1 comprises a polymer film, a primary layer coated on the polymer film, and a transparent electroconductive thin film formed on the primary layer.

The primary layer contains ultraviolet-curing resin, and particles of at least one silicon compound having an average diameter of 1 nm to 5 μm and selected form the group consisting of SiC_x, SiO_x, SiN_x, SiC_xO_y, SiC_xN_y, SiO_xN_y, and $SiC_xO_yN_z$. The particles of at least one silicon compound is included in 1-90 wt% to the ultraviolet-curing resin.

In claim 7, in addition to the above basic structure, it is further defined that each of the particles of silicon compound is provided with acryl groups, epoxy groups or carboxyl groups on its surface.

In claim 22, in the above basic structure, instead of the transparent electroconductive thin film, a multi-lamination film comprising at least one metal-compound layer and at least one electroconductive-metal layer is formed on the primary layer.

In Koyama et al. cited in the Action, a transparent conductive thin film includes a hard coating film 4, a transparent polymer film 2, an easy adhesion layer 3, and a transparent conductive film 5. The adhesion layer 3 is composed of an ionizing radiation curable resin binder, a thermoplastic resin binder, and two or more kinds of matting agents having different average diameters. The matting agents may be inorganic or organic micro particles, such as

silica, one kind having an average diameter of 1-15 μm and the other kind having an average diameter of 5-50 nm.

In claim 1, the primary layer contains ultraviolet-curing resin, and particles of at least one silicon compound having an average diameter of 1 nm to 5 μm. In Koyama et al., the adhesion layer includes the ionizing radiation curable resin binder, the thermoplastic resin binder and two or more kinds of matting agents with different average diameters. In the invention, the resin binder and the thermoplastic resin binder are not used.

Also, in the invention, the silicon compound with an average diameter of 1 nm to 5 μm is used, but the silicon compound is different from the matting agents with two different average diameters in Koyama et al.

Thus, the primary layer of the invention is not disclosed or suggested in Koyama et al.

In claim 7, in addition to the basic structure in claim 1, each of the particles of silicon compound is provided with acryl groups, epoxy groups or carboxyl groups on its surface, which is not disclosed or suggested in Koyama et al.

In claim 22, instead of the transparent electroconductive thin film in claim 1, the multi-lamination film comprising at least one metal-compound layer and at least one electroconductive-metal layer is formed on the primary layer. The multi-lamination film is not disclosed or suggested in Koyama et al.

In claims 41 and 42, the particles of silicon compound are defined to be selected form the group consisting of SiC_x, SiN_x, SiC_xO_y, SiC_xN_y, SiO_xN_y, and $SiC_xO_yN_z$. Namely, silica used in Koyama et al. is deleted.

In WO '251, a touch substrate 10 includes a hard coat layer 11, an undercoat layer 13, a conductive layer 14 and a contact layer 15. The undercoat layer 13 is composed of two layers 13a, 13b, and is made of a metal oxide with different refractive indexes. Silicon oxide may be used as the undercoat layer 13.

In claim 1 of the invention, the primary layer contains ultraviolet-curing resin, and particles of at least one silicon compound having an average diameter of 1 nm to 5 μm and selected form the group consisting of SiC_x, SiO_x, SiN_x, SiC_xO_y, SiC_xN_y, SiO_xN_y, and $SiC_xO_yN_z$. The particles of at least one silicon compound is included at 1-90 wt% to the ultraviolet-curing resin. Although the undercoat layer 13 of WO '251 may be made of silicon oxide, it is not formed of the resin and the particles, as recited in claim 1 of the invention. Thus, thee ratio of the silicon compound is not disclosed in WO '251. The features of claim 1 and other independent claims are not disclosed or suggested in WO '251.

In JP '599, a touch panel as shown in Fig. 3 is formed of a substrate 10, a first metal oxide layer 15, a second metal layer 16, and a third metal oxide layer 17. The first metal oxide layer 15 may be SiO_2, Al_2O_3, or TiO_3. The second layer 16 may be selected from Ag, Au and Cu. The third metal oxide layer 17 is an ITO layer.

In claim 1, the primary layer contains ultraviolet-curing resin, and particles of at least one silicon compound having an average diameter of 1 nm to 5 μm and selected form the group consisting of SiC_x, SiO_x, SiN_x, SiC_xO_y, SiC_xN_y, SiO_xN_y, and $SiC_xO_yN_z$. Although the first metal oxide layer 15 may be made of SiO_2, the layer is not formed of the ultraviolet-curing resin and the particles as specified in the invention. Therefore, JP '599 does not ~~disclose or suggest~~ the features of the invention.

As explained above, the features now claimed in the invention are not disclosed or suggested in the cited references. Even if the cited references are combined, the present invention is not obvious from the cited references.

Reconsideration and allowance are earnestly solicited.

Respectfully Submitted,

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